

## HOLDING APPARATUS

### ABSTRACT

Provided is a holding apparatus for applying an electrolytic plating treatment to a planar workpiece, and the holding apparatus can reduce an amount of plating that is deposited on an edge part of the planar workpiece. The holding apparatus for applying the electrolytic plating treatment to the planar workpiece has a rear member and a front member facing the rear member and having an opening part. The planar workpiece is disposed between the rear member and the front member. The front member has a plurality of electrodes and a plurality of first insulating parts. The plurality of electrodes and the plurality of first insulating parts cover the edge part of the planar workpiece in a width direction of the planar workpiece. Provided that an edge length of the planar workpiece in the width direction of the planar workpiece or an edge length of the opening part in a direction parallel to the width direction of the planar workpiece, whichever is smaller, is defined as 100, an edge part-covering length of the plurality of first insulating parts or the plurality of electrodes is 80 or more in the width direction of the planar workpiece within the edge length of the planar workpiece in the width direction of the planar workpiece.

FIG. 1